

SOT1162-1

plastic ball grid array package; 582 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA582
Package type industry code	BGA582
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-034D Compliant
Mounting method type	S (surface mount)
Issue date	29-12-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.8	-	27	27.2	mm
E	package width	26.8	-	27	27.2	mm
A	seated height	2.22	-	2.37	2.52	mm
A ₂	package height	1.82	-	1.87	1.92	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	582	-	



2. Package outline

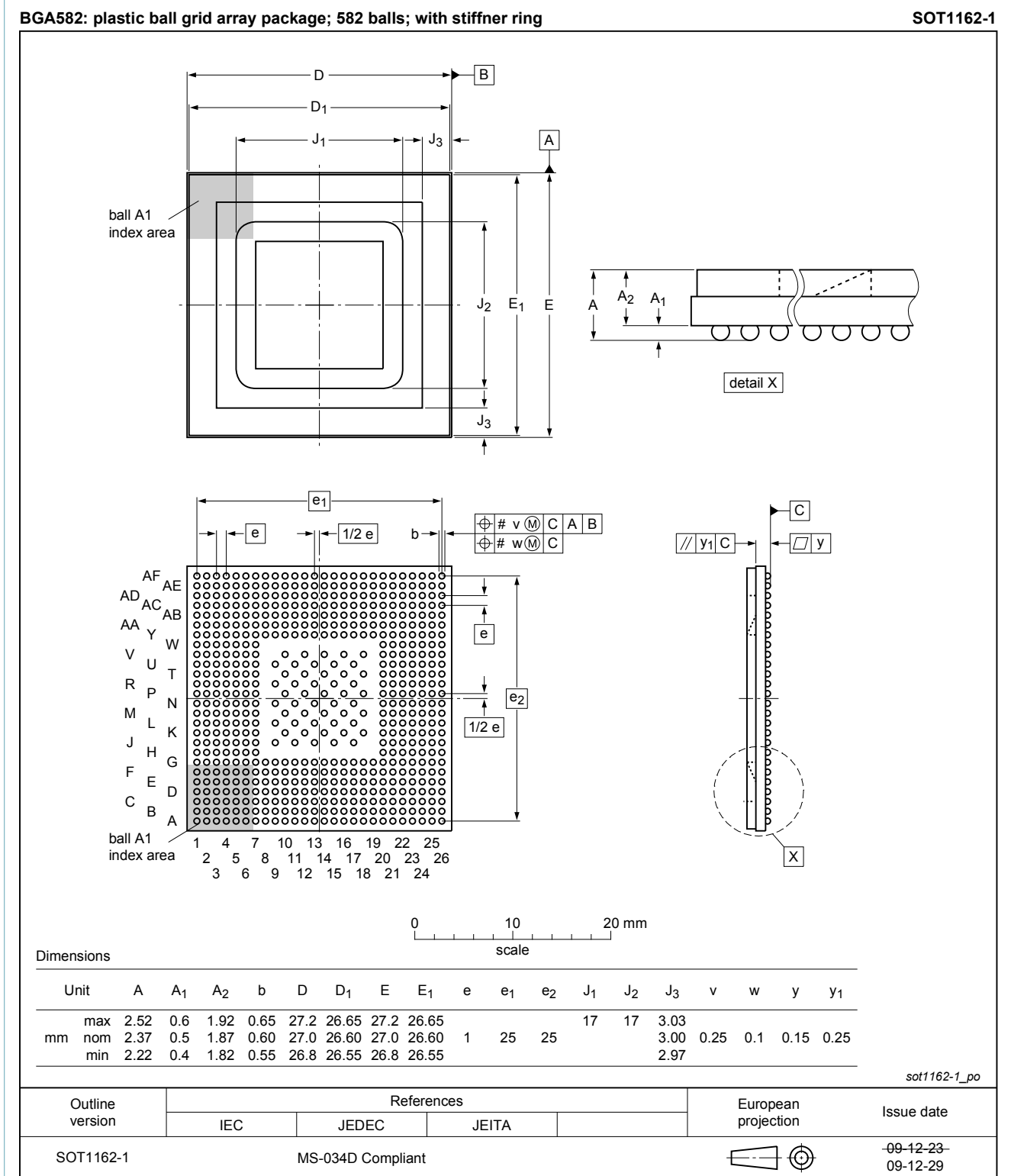


Fig. 1. Package outline BGA582 (SOT1162-1)

3. Legal information

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